

## P-Channel 30-V (D-S) MOSFET

PRODUCT SUMMARY							
V <sub>DS</sub> (V)	$R_{DS(on)}$ ( $\Omega$ )	I <sub>D</sub> (A) <sup>d</sup>	Q <sub>g</sub> (Typ.)				
- 30	0.018 at V <sub>GS</sub> = - 10 V	- 40	13 nC				
	0.025 at V <sub>GS</sub> = - 4.5 V	- 35	13110				

#### **FEATURES**

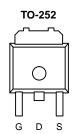
- Halogen-free According to IEC 61249-2-21 Definition
- TrenchFET® Power MOSFET
- 100 % R<sub>g</sub> Tested

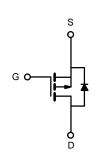
# Pb-free RoHS COMPLIANT

HALOGEN FREE



- Load Switch
- · Battery Switch





P-CI	nann	ei ivi	105	I

Parameter	Symbol	Limit	Unit		
Drain-Source Voltage	V <sub>DS</sub>	- 30	V		
Gate-Source Voltage	V <sub>GS</sub>	± 20	v		
	T <sub>C</sub> = 25 °C		- 40		
Continuous Drain Current /T 450 °C\	T <sub>C</sub> = 70 °C	1 ,	- 35		
Continuous Drain Current (T <sub>J</sub> = 150 °C)	T <sub>A</sub> = 25 °C	l <sub>D</sub>	- 30.0 <sup>a, b</sup>		
	T <sub>A</sub> = 70 °C		- 28 <sup>a, b</sup>	A	
Pulsed Drain Current	I <sub>DM</sub>	- 150			
Continuous Course Brain Binds Courset	T <sub>C</sub> = 25 °C		- 3.5		
Continuous Source-Drain Diode Current	T <sub>A</sub> = 25 °C	ls –	- 2.1 <sup>a, b</sup>		
	T <sub>C</sub> = 25 °C		40		
Mariana Barra Birahari	T <sub>C</sub> = 70 °C		27		
Maximum Power Dissipation	T <sub>A</sub> = 25 °C	P <sub>D</sub>	2.5 <sup>a, b</sup>	W	
	T <sub>A</sub> = 70 °C		1.6 <sup>a, b</sup>		
Operating Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	- 55 to 150	°C		

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Maximum Junction-to-Ambient <sup>a, c</sup>	t ≤ 10 s	R <sub>thJA</sub>	40	50	°C/W	
Maximum Junction-to-Foot	Steady State	R <sub>thJF</sub>	24	30	C/VV	

#### Notes

- a. Surface mounted on 1" x 1" FR4 board.
- b. t = 10 s.
- c. Maximum under Steady State conditions is 95 °C/W.
- d. Based on  $T_C = 25$  °C.



Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit
Static						
Drain-Source Breakdown Voltage	$V_{DS}$	$V_{GS} = 0 \text{ V}, I_D = -250 \mu\text{A}$	- 30			V
V <sub>DS</sub> Temperature Coefficient	$\Delta V_{DS}/T_{J}$	J I <sub>D</sub> = - 250 μA		- 31		mV/°C
V <sub>GS(th)</sub> Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	1D = - 250 μΑ		4.5		mv/°C
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	- 1.0		- 2.5	V
Gate-Source Leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA
Zoro Coto Voltago Droin Current	laaa	V <sub>DS</sub> = - 30 V, V <sub>GS</sub> = 0 V			- 1	μΑ
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = - 30 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 55 °C			- 5	
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} \le -5 \text{ V}, V_{GS} = -10 \text{ V}$	- 40			Α
David Course Co Otata Basista and	D	V <sub>GS</sub> = - 10 V, I <sub>D</sub> = - 7.0 A		0.018		Ω
Drain-Source On-State Resistance <sup>a</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> = - 4.5 V, I <sub>D</sub> = - 5.6 A		0.025		
Forward Transconductance <sup>a</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = - 15 V, I <sub>D</sub> = - 7.0 A		18		S
Dynamic <sup>b</sup>						
Input Capacitance	C <sub>iss</sub>			1455		
Output Capacitance	C <sub>oss</sub>	$V_{DS} = -15 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		180		pF
Reverse Transfer Capacitance	C <sub>rss</sub>			145		
Total Cata Charge	Q <sub>g</sub>	$V_{DS} = -15 \text{ V}, V_{GS} = -10 \text{ V}, I_{D} = -7.0 \text{ A}$		25	38	
Total Gate Charge			13	20	1	
Gate-Source Charge	$Q_{gs}$	$V_{DS} = -15 \text{ V}, V_{GS} = -4.5 \text{ V}, I_{D} = -7.0 \text{ A}$		3.5		- nC
Gate-Drain Charge	$Q_{gd}$			5.5		
Gate Resistance	R <sub>g</sub>	f = 1 MHz	0.4	2.0	4.0	Ω
Turn-On Delay Time	t <sub>d(on)</sub>			10	20	
ise Time t <sub>r</sub>		$V_{DD} = -15 \text{ V}, R_{L} = 2.7 \Omega$		13	20	
Turn-Off DelayTime	Off DelayTime $t_{d(off)}$ $I_{D}$			23	35	
Fall Time	t <sub>f</sub>			9	18	1
Turn-On Delay Time	t <sub>d(on)</sub>			38	57	ns
Rise Time	t <sub>r</sub>	$V_{DD} = -15 \text{ V}, R_{L} = 2.7 \Omega$		89	134	
Turn-Off DelayTime	t <sub>d(off)</sub>	<del>,</del>		22	33	1
Fall Time	t <sub>f</sub>			11	17	
Drain-Source Body Diode Characteris	tics					
Continous Source-Drain Diode Current	I <sub>S</sub>	T <sub>C</sub> = 25 °C			- 6.5	Α
Pulse Diode Forward Current	I <sub>SM</sub>				- 30	] ^
Body Diode Voltage	V <sub>SD</sub>	I <sub>S</sub> = - 5.6 A, V <sub>GS</sub> = 0 V		- 0.71	- 1.2	V
Body Diode Reverse Recovery Time t <sub>rr</sub>				22	33	ns
Body Diode Reverse Recovery Charge	$Q_{rr}$	L = 56 A dl/dt = 100 A/up T = 25 °C		17	26	nC
Reverse Recovery Fall Time	t <sub>a</sub>	$I_F = -5.6 \text{ A}, \text{ dI/dt} = 100 \text{ A/}\mu\text{s}, T_J = 25 ^{\circ}\text{C}$		13		ns
Reverse Recovery Rise Time	t <sub>b</sub>	7		9		1115

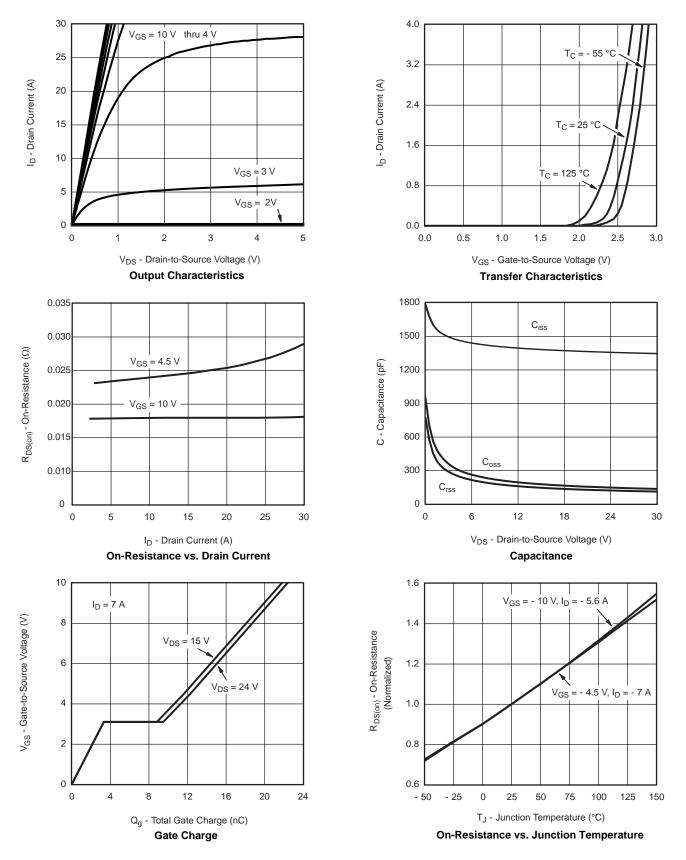
#### Notes:

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

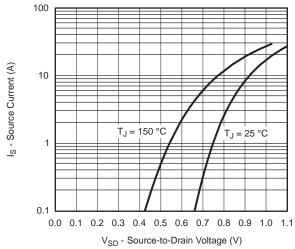
a. Pulse test; pulse width  $\leq 300~\mu s,$  duty cycle  $\leq 2~\%.$ 

b. Guaranteed by design, not subject to production testing.

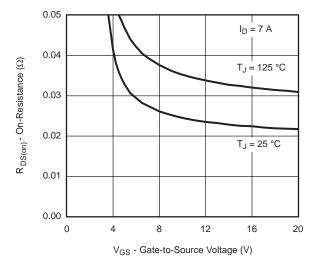




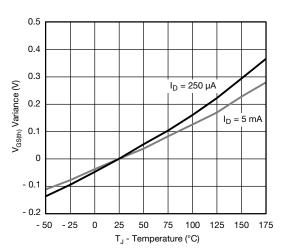




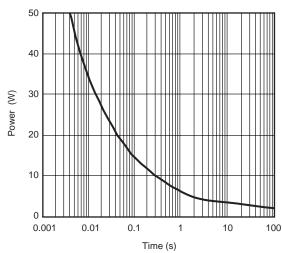
#### Source-Drain Diode Forward Voltage



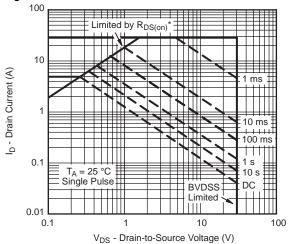
On-Resistance vs. Gate-to-Source Voltage



**Threshold Voltage** 



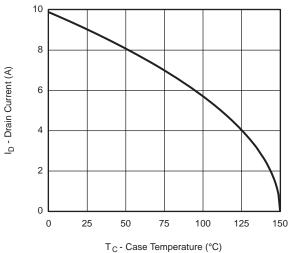
Single Pulse Power, Junction-to-Ambient



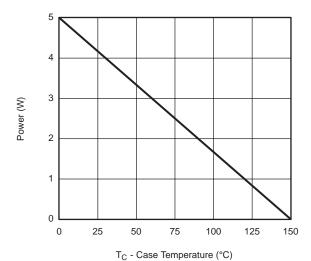
\*  $V_{GS}$  > minimum  $V_{GS}$  at which  $R_{DS(on)}$  is specified

Safe Operating Area

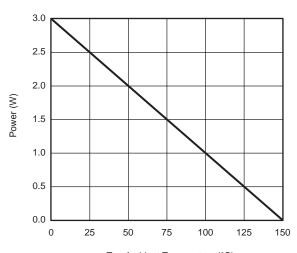




#### **Current Derating\***



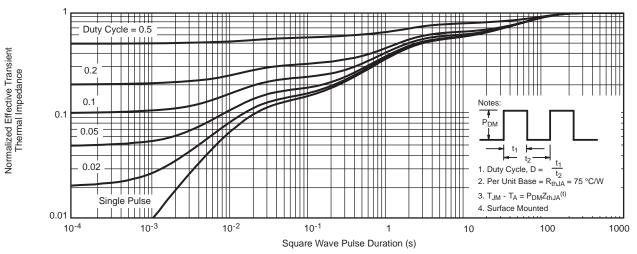
Power, Junction-to-Foot



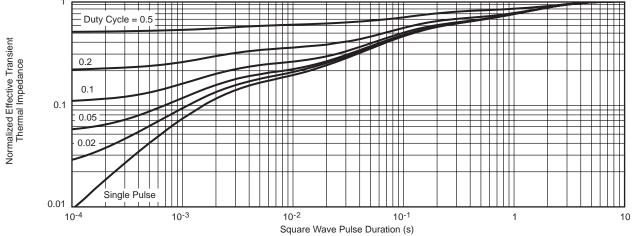
T<sub>A</sub> - Ambient Temperature (°C) Power Derating, Junction-to-Ambient

<sup>\*</sup> The power dissipation  $P_D$  is based on  $T_{J(max)}$  = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package





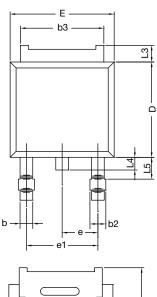
Normalized Thermal Transient Impedance, Junction-to-Ambient

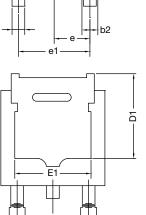


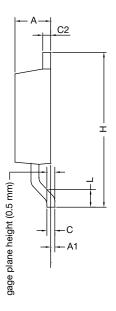
Normalized Thermal Transient Impedance, Junction-to-Foot



## **TO-252AA CASE OUTLINE**







	MILLIMETERS		INCHES			
DIM.	MIN.	MAX.	MIN.	MAX.		
Α	2.18	2.38	0.086	0.094		
A1	-	0.127	-	0.005		
b	0.64	0.88	0.025	0.035		
b2	0.76	1.14	0.030	0.045		
b3	4.95	5.46	0.195	0.215		
С	0.46	0.61	0.018	0.024		
C2	0.46	0.89	0.018	0.035		
D	5.97	6.22	0.235	0.245		
D1	5.21	-	0.205	-		
Е	6.35	6.73	0.250	0.265		
E1	4.32	-	0.170	-		
Н	9.40	10.41	0.370	0.410		
е	2.28 BSC		0.090 BSC			
e1	4.56 BSC		0.180 BSC			
L	1.40	1.78	0.055	0.070		
L3	0.89	1.27	0.035	0.050		
L4	-	1.02	-	0.040		
L5	1.14	1.52	0.045	0.060		
ECN: X12-0247-Rev. M, 24-Dec-12						

ECN: X12-0247-Rev. M, 24-Dec-DWG: 5347

#### Note

• Dimension L3 is for reference only.



#### **RECOMMENDED MINIMUM PADS FOR DPAK (TO-252)**



Recommended Minimum Pads Dimensions in Inches/(mm)



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